

Product/Process Change Notice - PCN 15_0204 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: ADuM3210W/ADuM3211W Die Revision and Data Sheet Change

Publication Date: 09-Nov-2015

Effectivity Date: 07-Feb-2016 (the earliest date that a customer could expect to receive changed material)

Revision Description:

| | Release | |
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Description Of Change

Die Changes:

- 1. Increased pulse width of edge pulses and refresh pulses.
- 2. Increased separation between consecutive pulses on rising edge and refresh high pulses.
- 3. Additional layer of polyimide passivation on top of the non-coil die.

Data Sheet Changes:

- 1. Increased Idd-Dynamic current specifications at 10Mbps and 25Mbps operating conditions. See data sheet specification comparison attachment for resulting values.
- 2. Changed Voh/Vol test conditions from lox=4mA/4mA to lox=3.2mA/3.2mA.

Reason For Change

Die Changes:

- 1. Ensure receiver can reliably detect all edge pulses and all refresh pulses.
- 2. Ensure 2nd pulse on rising edge or refresh high is consistently detected by receiver.
- 3. Polyimide offers the following advantages: improved ESD robustness, enhanced protection against die scratches, package stresses, surface ESD/EOS events and radiation.

Data Sheet Changes:

- 1. Increase in size of existing capacitors in receiver block caused increase in Idd-Dynamic current.
- 2. Express Voh/Vol levels with a load equal to the current required to drive two standard TTL gates.

Impact of the change (positive or negative) on fit, form, function & reliability

No change to fit, form, or reliability. Improved functionality.

Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_15_0204_Rev_-_ADuM321xW_Qualification_Results_Summary.pdf

Attachment 2: Type: Datasheet Specification Comparison

ADI_PCN_15_0204_Rev_-_ADUM3210W_IDD_Specification_Comparison.pdf

Attachment 3: Type: Datasheet Specification Comparison

ADI_PCN_15_0204_Rev_-_ADUM3211W_IDD_Specification_Comparison.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com Europe: PCN_Europe@analog.com Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

| Appendix A - Affected ADI Models | | | | | | |
|---|-----------------------------|-----------------------------|-----------------------------|-----------------------------|--|--|
| Added Parts On This Revision - Product Family / Model Number (12) | | | | | | |
| ADUM3210 / ADUM3210WARZ | ADUM3210 / ADUM3210WARZ-RL7 | ADUM3210 / ADUM3210WBRZ | ADUM3210 / ADUM3210WBRZ-RL7 | ADUM3210 / ADUM3210WCRZ | | |
| ADUM3210 / ADUM3210WCRZ-RL7 | ADUM3211 / ADUM3211WARZ | ADUM3211 / ADUM3211WARZ-RL7 | ADUM3211 / ADUM3211WBRZ | ADUM3211 / ADUM3211WBRZ-RL7 | | |
| ADUM3211 / ADUM3211WCRZ | ADUM3211 / ADUM3211WCRZ-RL7 | | | | | |

| Appendix B - Revision History | | | | | |
|-------------------------------|--------------|------------------|-----------------|--|--|
| Rev | Publish Date | Effectivity Date | Rev Description | | |
| Rev | 09-Nov-2015 | 07-Feb-2016 | Initial Release | | |
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Analog Devices, Inc.

Docld:3434 Parent Docld:3416 Layout Rev:7